



Material Content Data Sheet



Sales Product Name				IPD60R180C7		Issued		1. June 2016	
MA#				MA001498636					
Package				PG-TO252-3-313		Weight*		321.28 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.951	1.23	1.23	12298	12298	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		458		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		138		
	non noble metal	copper	7440-50-8	147.096	45.78	45.84	457840	458436	
wire	non noble metal	aluminium	7429-90-5	18.178	5.66	5.66	56580	56580	
encapsulation	organic material	carbon black	1333-86-4	1.241	0.39		3863		
	plastics	epoxy resin	-	21.721	6.76		67606		
	inorganic material	silicondioxide	60676-86-0	101.157	31.49	38.64	314853	386322	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.16	1.16	11641	11641	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4421	4432	
solder	noble metal	silver	7440-22-4	0.085	0.03		263		
	non noble metal	tin	7440-31-5	0.068	0.02		210		
	non noble metal	lead	7439-92-1	3.229	1.00	1.05	10050	10523	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	5.97	5.98	59690	59768	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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